



arm

# Dynamic Energy Model to handle leakage power

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# Agenda

- + What is the Energy Model (EM) in Linux kernel
- + Relation between Energy Aware Scheduler (EAS) and EM
- + Power and temperature relation in recent SoCs
- + Runtime adjustable EM
- + Other use cases

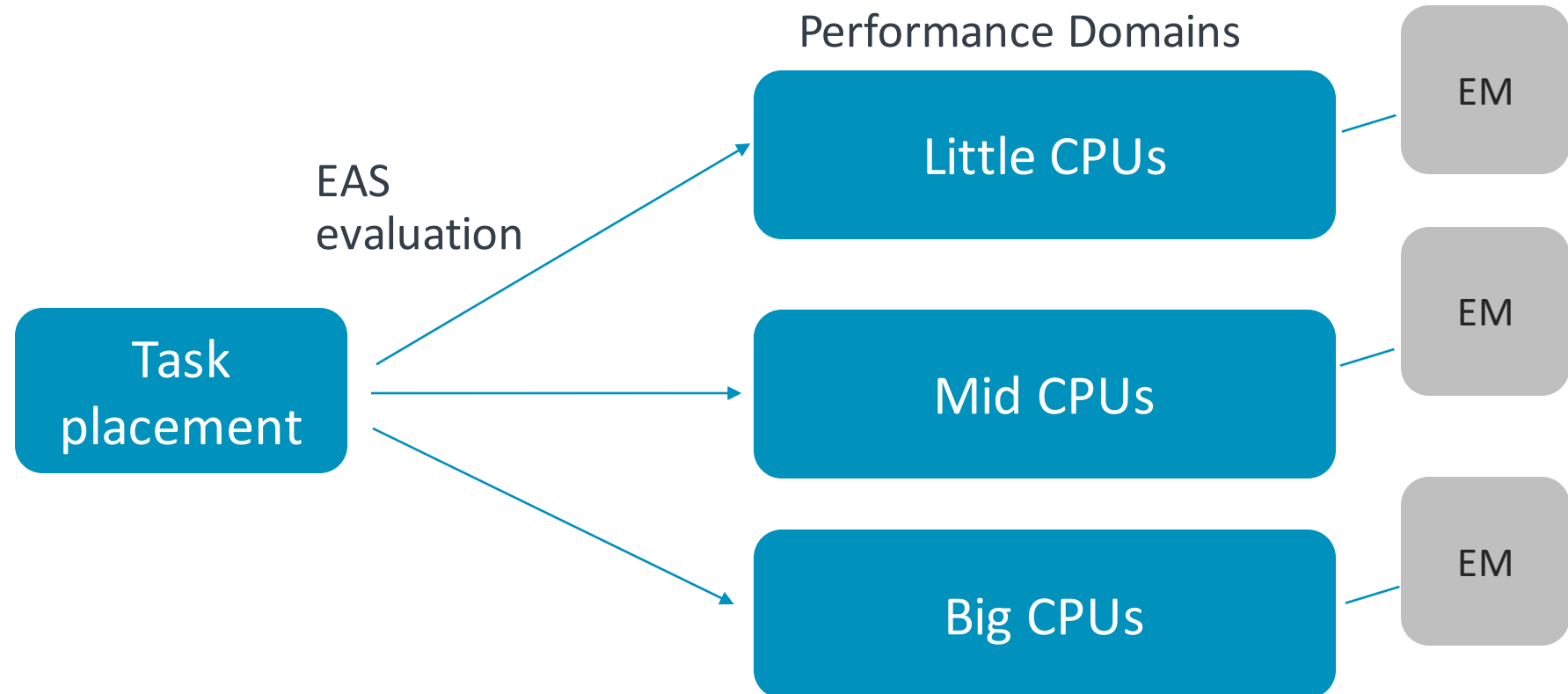
# What is the Energy Model (EM) in Linux kernel

- + A constant array of frequency, power and cost tuples (setup during boot)
- + Contains 'cost' (based on power) for EAS to speed up calculation
- + Decision/information source for EAS to make task placement decisions
- + There is one EM for each Performance Domain

Frequency [kHz]	Power [uW]	cost
500000	79613	446151
851000	148208	487989
...	...	...
2704000	1801528	1866820
2802000	2158976	2158976

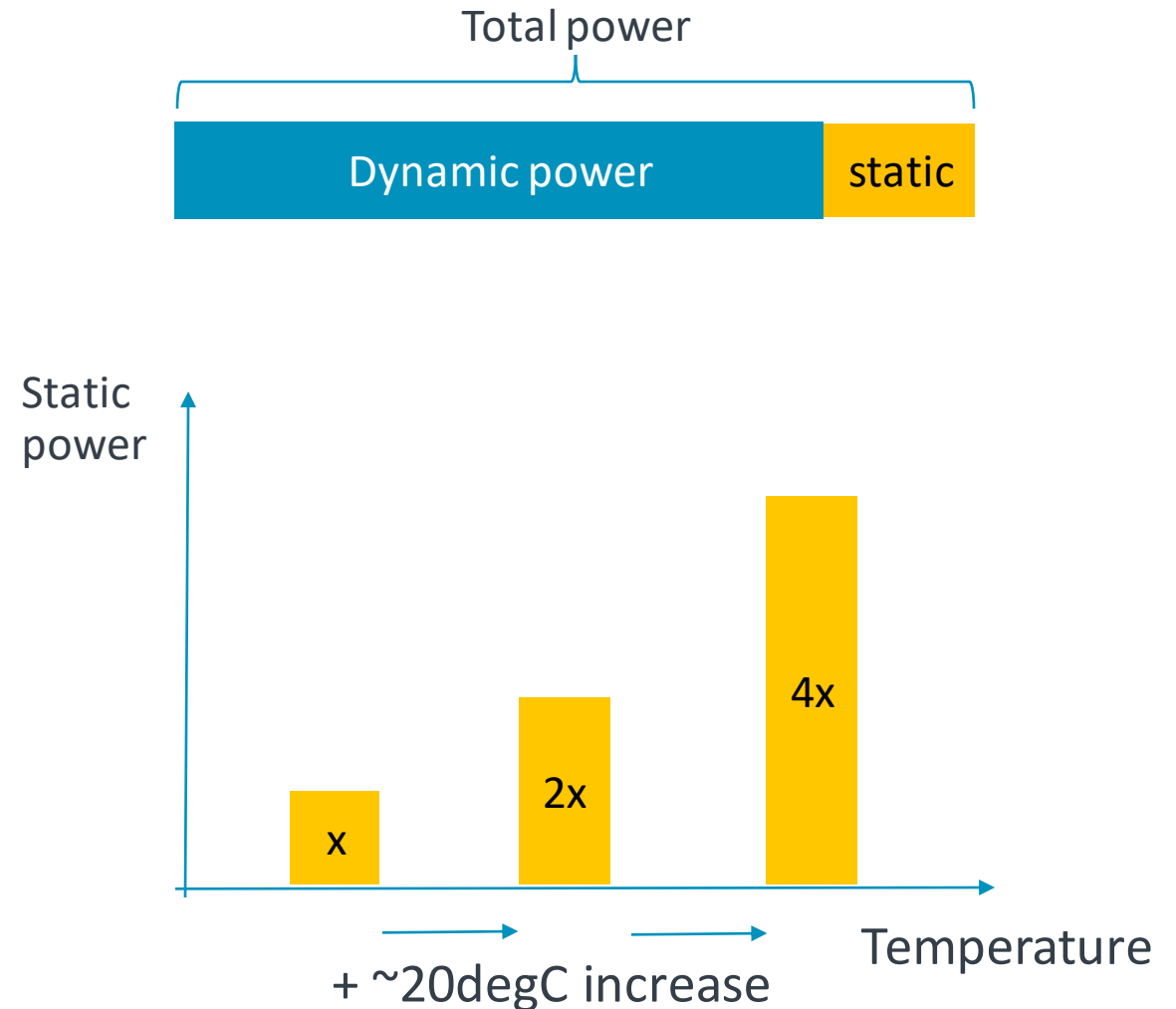
# Relation between Energy Aware Scheduler (EAS) and EM

- + EAS tries to minimize energy by looking at all possible Performance Domains (Big CPUs, Medium (Mid) CPUs, Little CPUs) when selecting the CPU for a woken-up task
- + EAS uses EM information for comparisons



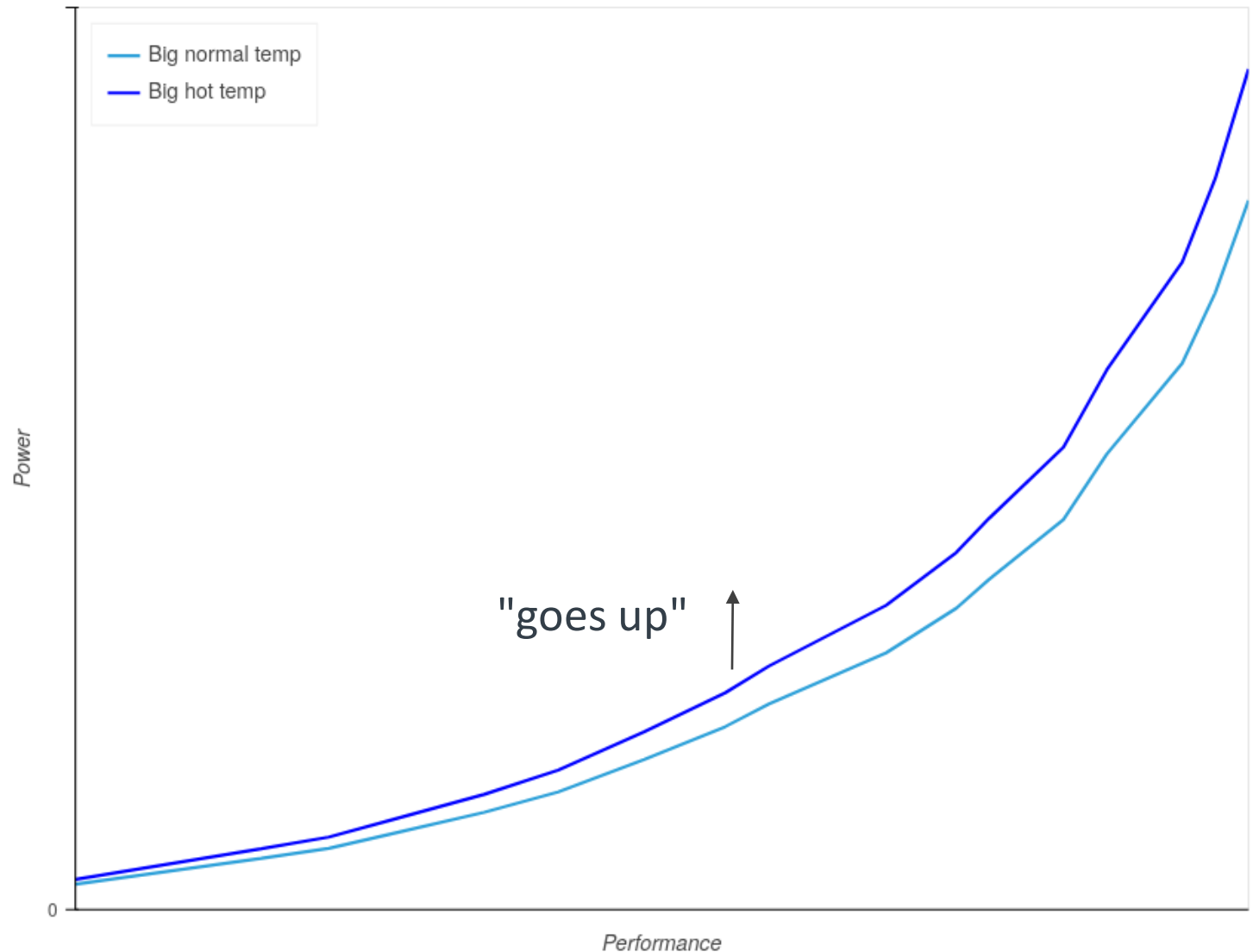
# Power and temperature relation in recent SoCs

- + Total power: dynamic + static power
- + The static power (leakage) increases with temperature
- + SoC has different types of CPUs, which are built with different goals: performance or power efficiency
- + Performance cores (Big CPU) leak more
- + Performance cores are more affected by the temperature increase than efficient cores (Mid CPU)



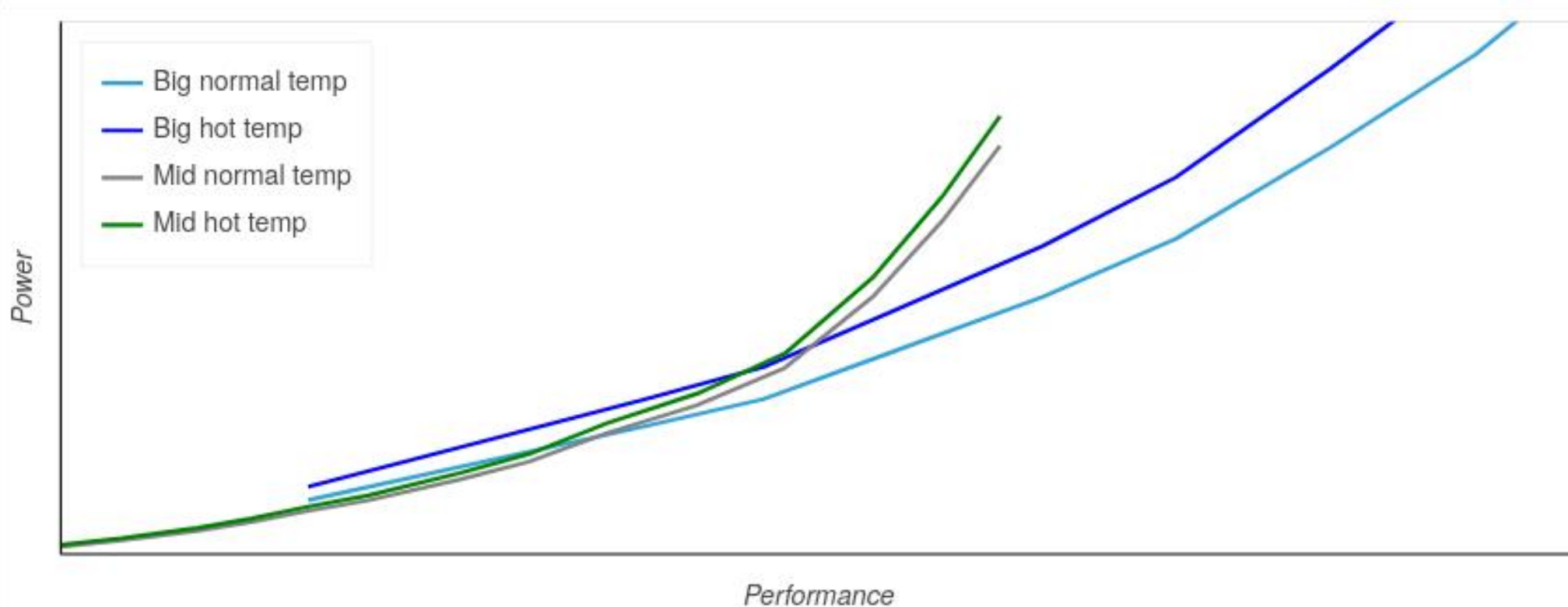
# Power and temperature relation in recent SoCs

- + Temperature of the SoC can be increased by adjacent devices (e.g. GPU)
  - e.g. increases the CPUs temperature by +20..30degC more than their normal temperature at the same frequency
- + Power vs. Performance curve of a CPU can "go up"
  - Big CPU's curve would go up a bit more



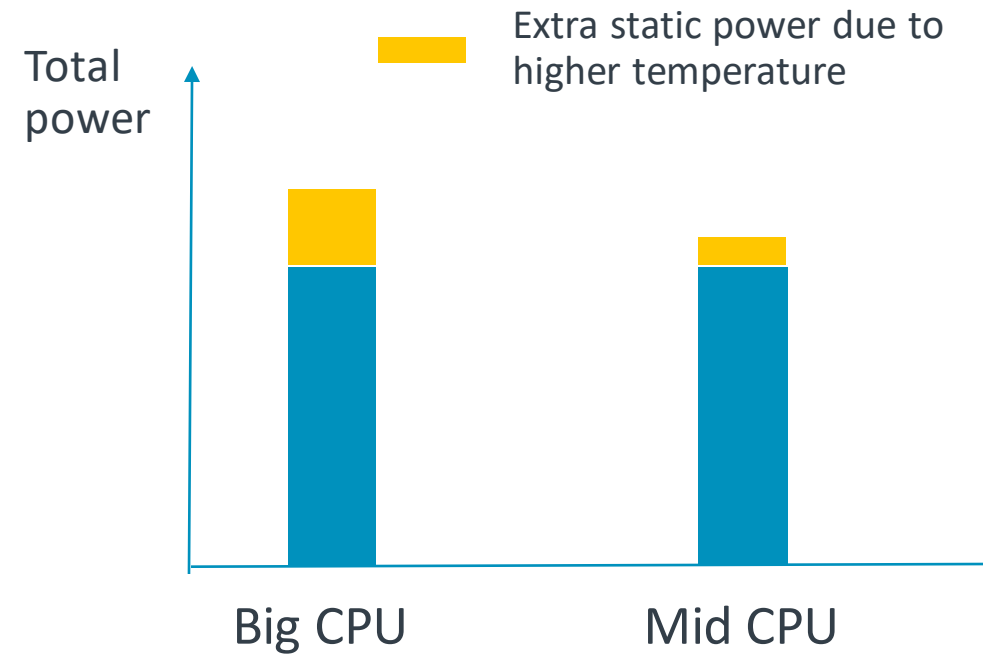
# Power and temperature relation in recent SoCs

- + Big CPU and Mid CPU curves position is different, therefore EAS decision should also be different



# Power and temperature relation in recent SoCs

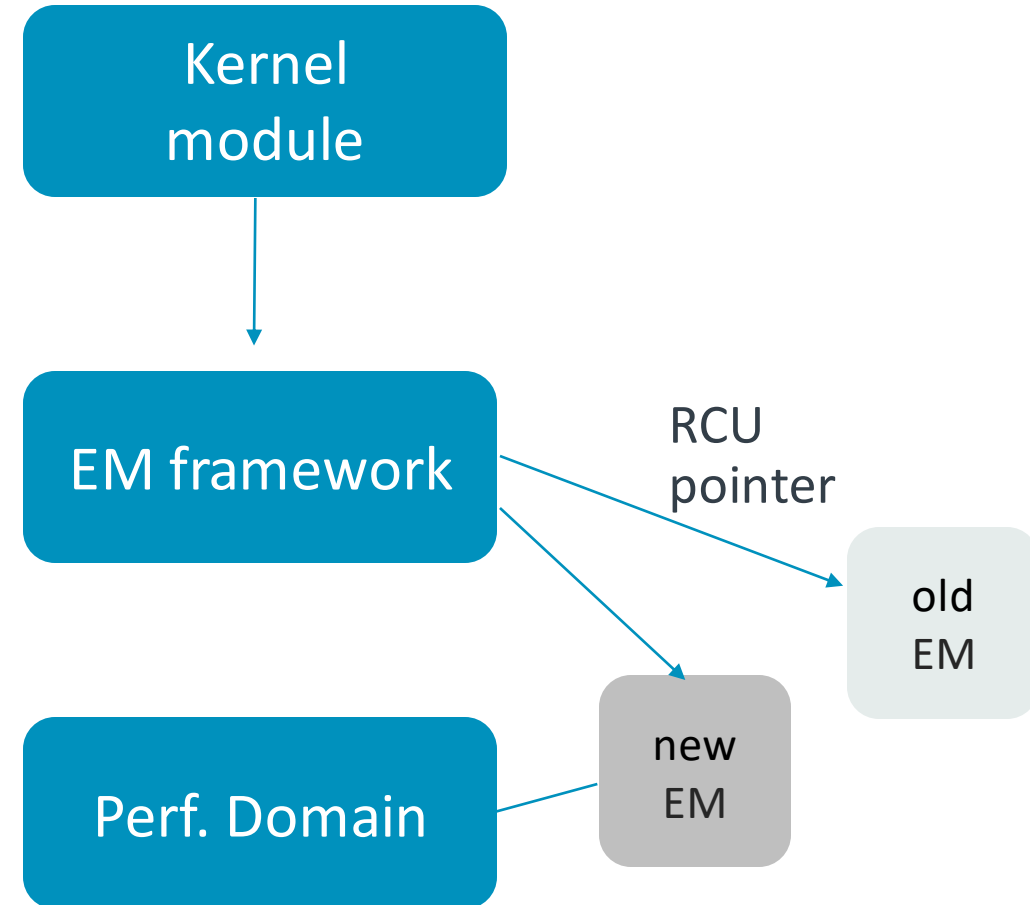
- + Example power plots from a real phone (2021)
- + CPU's temperature +20degC vs. normal due to GPU heat
- + Big CPU Power increase
  - +15 ... 18.5%
- + Mid CPU Power increase
  - +5 ... 8%





# Runtime adjustable EM

- + Runtime EM change requested by a kernel module
  - No sysfs interface for a user-space
  - No thermal framework changes
- + EM main data structure is allocated by the EM framework
  - EM is the memory owner (task scheduler requirement)
- + New 'power' values are populated by the caller (kernel module)
- + New EM data is used by the EAS during task placement (after RCU re-assignment for the pointer)



# Other use cases

- + allow to provide (after boot) the total power values for each frequency not limited to any formula or DT data
- + allow to provide power values proper for a given SoC manufactured with different **binning** and read from FW or kernel module
- + change EM at runtime for a specific workload on screen, which is utilizing HW resources differently (Gaming, video recording, web browsing)

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Thank You

Danke

Gracias

Grazie

谢谢

ありがとう

Asante

Merci

감사합니다

धन्यवाद

Kiitos

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# Links

+ <https://android-review.googlesource.com/c/kernel/common/+1906500/1>